

Shixin CHEN

Ph.D. Candidate ❀ Department of Computer Science and Engineering
The Chinese University of Hong Kong ❀ Supervisor: Prof. Bei Yu
Email: sxchen@link.cuhk.edu.hk ❀ sxchen.cn



EDUCATION

The Chinese University of Hong Kong (CUHK)

Ph.D. in Computer Science and Engineering
Supervisor: Prof. Bei Yu

Aug. 2022 – Aug. 2026
Hong Kong

Nanjing University (NJU)

B.Eng. in VLSI Design and System Integration, Elite Class, Rank 2/35

Sept. 2018 – June 2022
Nanjing, China

RESEARCH INTERESTS

- Design Space Exploration of Architecture
- 3D/2.5D IC and Chiplet
- Analog Design and Optimization
- Hardware Accelerator
- Machine Learning in EDA

PUBLICATIONS

* represents equal contribution.

Conference Papers

[C8] Yapeng Li, Peng Xu, **Shixin Chen**, Jindong Tu, Tongkai Wu, Chong Tong, Bei Yu, Tinghuan Chen, “AMigration: Analog Placement Migration via Adaptive Constraints Relaxation,” *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, San Jose, Nov. 8–12, 2026.

[C7] **Shixin Chen**, Peng Xu, Yapeng Li, Tinghuan Chen, Bei Yu, “PatchWork: A Patch-Driven Framework for Efficient Analog Layout Automation via Legacy Knowledge Reuse,” *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, San Jose, California, USA, Nov. 8–12, 2026.

[C6] Zixuan Li*, Kanglin Tian*, Fan Hu, Zirui Li, Xinyue Wu, Hengyuan Zhang, **Shixin Chen**, Jianwang Zhai, Xinfei Guo, Kang Zhao, “ChiPlanner: Physically-Aware and Timing-Driven Design Planner for 2.5D Multi-Chiplet Systems,” *ACM/IEEE Design Automation Conference (DAC)*, Long Beach, USA, Jul. 26–29, 2026.

[C5] **Shixin Chen***, Peng Xu*, Yapeng Li, Tinghuan Chen, Bei Yu, “IP-Matcher: An Efficient One-to-Many Matching Framework for Analog Circuit Design and Reusing,” *IEEE/ACM Design, Automation and Test in Europe (DATE)*, Verona, Italy, Apr. 20–22, 2026.

[C4] **Shixin Chen**, Hengyuan Zhang, Jianwang Zhai, Bei Yu, “CHASE: A CHiplet Architecture Simulation and Exploration Framework with Decoupled Multi-Fidelity Optimization,” *ACM International Symposium on Physical Design (ISPD)*, Bonn, Germany, Mar. 15–18, 2026.

[C3] **Shixin Chen**, Hengyuan Zhang, Zichao Ling, Jianwang Zhai, Bei Yu, “The Survey of 2.5D Integrated Architecture: An EDA Perspective,” *IEEE/ACM Asia and South Pacific Design Automation Conference (ASP-DAC)*, Japan, Jan. 21–23, 2025. (Invited Paper)

[C2] Mingjun Li*, Pengjia Li*, Shuo Yin, **Shixin Chen**, Beichen Li, Chong Tong, Jianlei Yang, Tinghuan Chen, Bei Yu, “[WinoGen: A Highly Configurable Winograd Convolution IP Generator for Efficient CNN Acceleration on FPGA](#),” *ACM/IEEE Design Automation Conference (DAC)*, 2024.

[C1] **Shixin Chen**, Su Zheng, Chen Bai, Wenqian Zhao, Shuo Yin, Yang Bai, Bei Yu, “[SoC-Tuner: An Importance-guided Exploration Framework for DNN-targeting SoC Design](#),” *IEEE/ACM Asia and South Pacific Design Automation Conference (ASP-DAC)*, South Korea, Jan. 22–25, 2024.

Journal Papers

[J3] Peng Xu, Su Zheng, Mingzi Wang, Ziyang Yu, **Shixin Chen**, Tinghuan Chen, Keren Zhu, Tsung-Yi Ho, Bei Yu, “[Rank-DSE: Neural Pareto Comparator of Microarchitecture Design Space Exploration](#),” *ACM Transactions on Design Automation of Electronic Systems (TODAES)*, vol. 30, no. 5, pp. 71:1–71:24, 2025.

[J2] **Shixin Chen**, Shanyi Li, Zhen Zhuang, Su Zheng, Zheng Liang, Tsung-Yi Ho, Bei Yu, Alberto L. Sangiovanni-Vincentelli, “[Floorplet: Performance-aware Floorplan Framework for Chiplet Integration](#),” *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 43, no. 6, pp. 1638–1649, 2024.

[J1] Yang Bai, Xufeng Yao, Qi Sun, Wenqian Zhao, **Shixin Chen**, Zixiao Wang, Bei Yu, “[GTCO: Graph and Tensor Co-Design for Transformer-based Image Recognition on Tensor Cores](#),” *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 43, no. 2, pp. 586–599, 2024.

SELECTED AWARDS

Award and Year

Hong Kong PhD Fellowship Scholarship (HKPFS), 2022
CUHK Vice-Chancellor’s PhD Scholarship, 2022
Chenxue Overseas Study Scholarship, 2022
Outstanding Graduate of Jiangsu Province, 2022
The Star of Self-Improvement, 2021
The Person of the Year of NJU, 2021
The Dongliang Special Scholarship, 2021
National Scholarship, 2019
People’s Scholarship, 2019–2021
National Encouragement Scholarship, 2020–2021
Student Model of Jiangsu Province, 2020
The Yang Lanyun Leadership Scholarship, 2020
Electronic Design Competition Second Prize, 2020
Sichuan Chamber of Commerce Scholarship, 2019

Awarding Institution

Research Grants Council of Hong Kong
The Chinese University of Hong Kong
Nanjing University
The Education Department of Jiangsu Province
National Union of Students of PRC
Nanjing University
Nanjing University
Education Ministry of PRC
Nanjing University
Education Ministry of PRC
Jiangsu Province
Nanjing University
Jiangsu Province
Sichuan Chamber of Commerce of Jiangsu Province

EXPERIENCES

SmartMore Co., Ltd.

Research Intern, Heterogeneous Computing Group
Topic: Hardware Accelerator for Super-resolution Video

Jul. 2021 – Sept. 2022

Shenzhen, Guangdong Province

Huawei Noah’s Ark Lab

Research Intern, AI4EDA Group
Topic: Large Language Model for Hardware Verification

Sept. 2023 – Dec. 2023

Shenzhen, Guangdong Province

ACADEMIC SERVICE

Conference Reviewer

- ACM International Symposium on Physical Design (ISPD), 2024

- ACM/IEEE Asia and South Pacific Design Automation Conference (ASP-DAC), 2025

Journal Reviewer

- IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)
- IEEE Transactions on Very Large Scale Integration Systems (TVLSI)
- ACM Transactions on Design Automation of Electronic Systems (TODAES)

SKILLS

Software Languages C, C++, Python, Bash

Hardware Languages SystemVerilog, Chisel

Tools Xilinx Vivado, PyTorch, L^AT_EX

Frameworks [Chipyard](#), [Gem5](#)

Hobbies Guitar, Chinese Calligraphy, Badminton

TEACHING

- CSCI2010, Fall 2023, Digital Logic Design Laboratory
- CSCI3420, Spring 2023, Computer Organization and Design
- CSCI3420, Spring 2024, Computer Organization and Design